



## Material Content Data Sheet



<b>Sales Product Name</b>		IPG16N10S4-61A		<b>Issued</b>		20. July 2018			
<b>MA#</b>		MA001096390							
<b>Package</b>		PG-TDSON-8-10		<b>Weight*</b>		98.12 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.337	1.36	1.36	13630	13630	
leadframe	non noble metal	iron	7439-89-6	0.046	0.05		473		
	inorganic material	phosphorus	7723-14-0	0.014	0.01		142		
	non noble metal	copper	7440-50-8	46.380	47.29	47.35	472675	473290	
wire	non noble metal	aluminium	7429-90-5	0.725	0.74	0.74	7390	7390	
encapsulation	organic material	carbon black	1333-86-4	0.091	0.09		932		
	plastics	epoxy resin	-	6.490	6.61		66140		
	inorganic material	silicondioxide	60676-86-0	39.122	39.87	46.57	398705	465777	
leadfinish	non noble metal	tin	7440-31-5	1.396	1.42	1.42	14231	14231	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		15		
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6146	6161	
solder	noble metal	silver	7440-22-4	0.048	0.05		488		
	non noble metal	tin	7440-31-5	0.038	0.04		390		
	non noble metal	lead	7439-92-1	1.829	1.86	1.95	18643	19521	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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